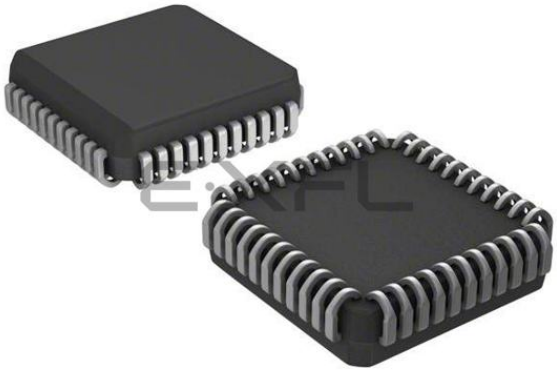

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	8MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	8KB (4K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17lc43t-08i-l

TABLE 1-1: PIC17CXX FAMILY OF DEVICES

Features		PIC17C42	PIC17CR42	PIC17C42A	PIC17C43	PIC17CR43	PIC17C44
Maximum Frequency of Operation		25 MHz	33 MHz	33 MHz	33 MHz	33 MHz	33 MHz
Operating Voltage Range		4.5 - 5.5V	2.5 - 6.0V	2.5 - 6.0V	2.5 - 6.0V	2.5 - 6.0V	2.5 - 6.0V
Program Memory x16	(EPROM)	2K	-	2K	4K	-	8K
	(ROM)	-	2K	-	-	4K	-
Data Memory (bytes)		232	232	232	454	454	454
Hardware Multiplier (8 x 8)		-	Yes	Yes	Yes	Yes	Yes
Timer0 (16-bit + 8-bit postscaler)		Yes	Yes	Yes	Yes	Yes	Yes
Timer1 (8-bit)		Yes	Yes	Yes	Yes	Yes	Yes
Timer2 (8-bit)		Yes	Yes	Yes	Yes	Yes	Yes
Timer3 (16-bit)		Yes	Yes	Yes	Yes	Yes	Yes
Capture inputs (16-bit)		2	2	2	2	2	2
PWM outputs (up to 10-bit)		2	2	2	2	2	2
USART/SCI		Yes	Yes	Yes	Yes	Yes	Yes
Power-on Reset		Yes	Yes	Yes	Yes	Yes	Yes
Watchdog Timer		Yes	Yes	Yes	Yes	Yes	Yes
External Interrupts		Yes	Yes	Yes	Yes	Yes	Yes
Interrupt Sources		11	11	11	11	11	11
Program Memory Code Protect		Yes	Yes	Yes	Yes	Yes	Yes
I/O Pins		33	33	33	33	33	33
I/O High Current Capability	Source	25 mA	25 mA	25 mA	25 mA	25 mA	25 mA
	Sink	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)	25 mA(1)
Package Types		40-pin DIP 44-pin PLCC 44-pin MQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP	40-pin DIP 44-pin PLCC 44-pin MQFP 44-pin TQFP

Note 1: Pins RA2 and RA3 can sink up to 60 mA.

NOTES:

6.8 Bank Select Register (BSR)

The BSR is used to switch between banks in the data memory area (Figure 6-13). In the PIC17C42, PIC17CR42, and PIC17C42A only the lower nibble is implemented. While in the PIC17C43, PIC17CR43, and PIC17C44 devices, the entire byte is implemented. The lower nibble is used to select the peripheral register bank. The upper nibble is used to select the general purpose memory bank.

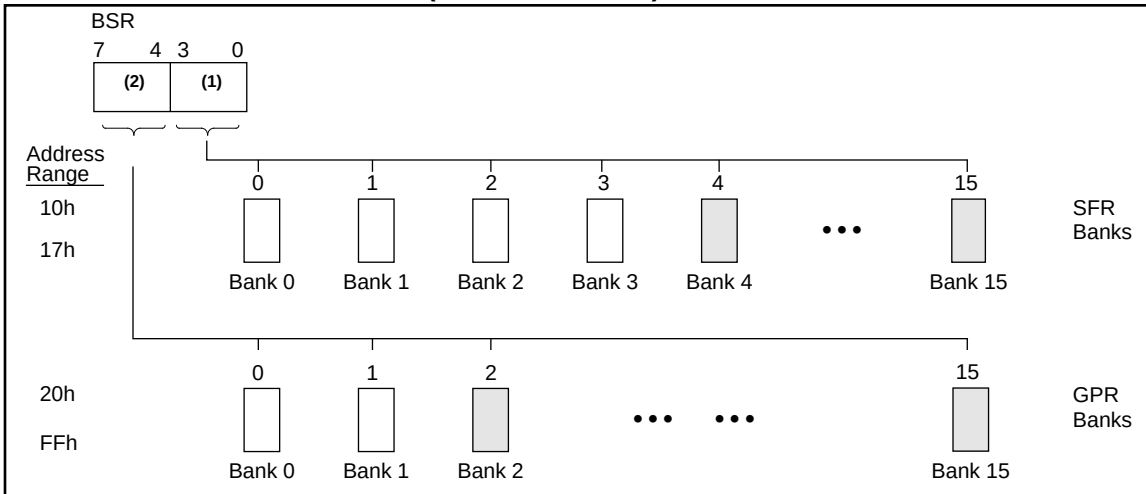
All the Special Function Registers (SFRs) are mapped into the data memory space. In order to accommodate the large number of registers, a banking scheme has been used. A segment of the SFRs, from address 10h to address 17h, is banked. The lower nibble of the bank select register (BSR) selects the currently active "peripheral bank." Effort has been made to group the peripheral registers of related functionality in one bank. However, it will still be necessary to switch from bank to bank in order to address all peripherals related to a single task. To assist this, a `MOVLB bank` instruction is in the instruction set.

For the PIC17C43, PIC17CR43, and PIC17C44 devices, the need for a large general purpose memory space dictated a general purpose RAM banking scheme. The upper nibble of the BSR selects the currently active general purpose RAM bank. To assist this, a `MOVLR bank` instruction has been provided in the instruction set.

If the currently selected bank is not implemented (such as Bank 13), any read will read all '0's. Any write is completed to the bit bucket and the ALU status bits will be set/cleared as appropriate.

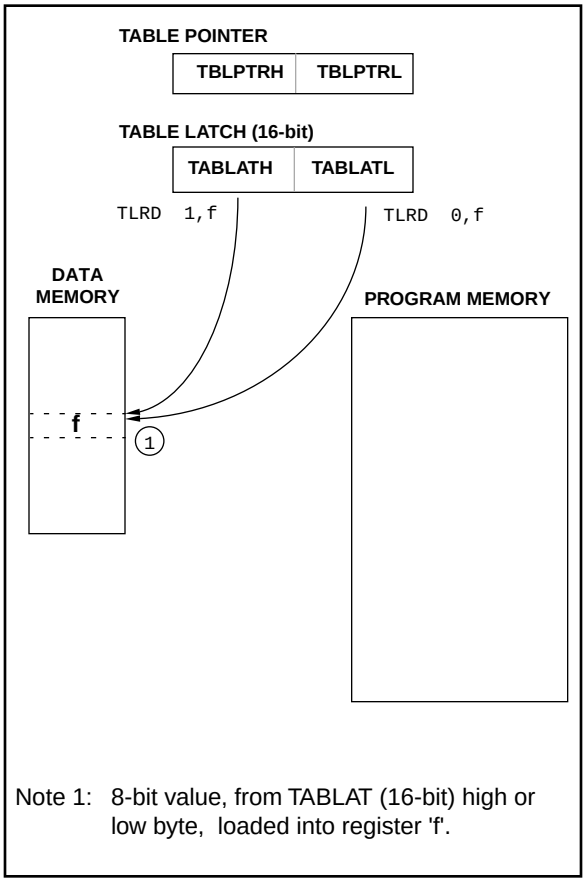
Note:	Registers in Bank 15 in the Special Function Register area, are reserved for Microchip use. Reading of registers in this bank may cause random values to be read.

FIGURE 6-13: BSR OPERATION (PIC17C43/R43/44)



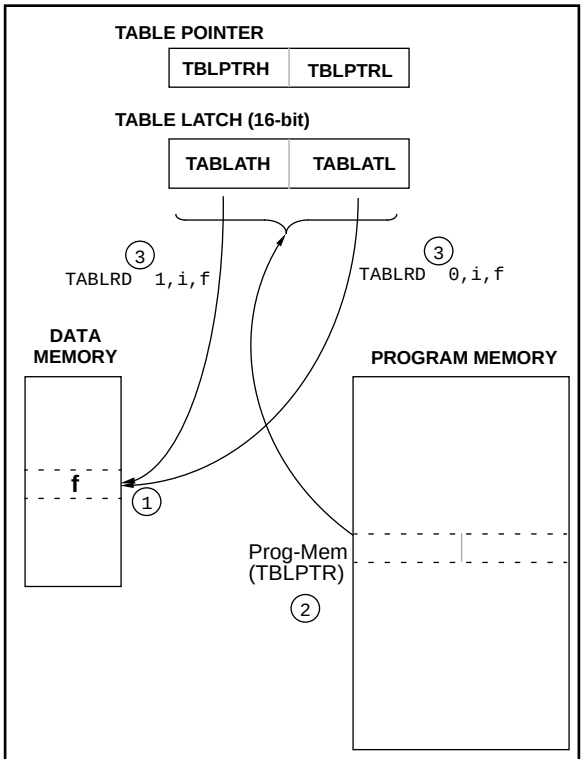
Note 1: Only Banks 0 through Bank 3 are implemented. Selection of an unimplemented bank is not recommended**.**
Bank 15 is reserved for Microchip use, reading of registers in this bank may cause random values to be read.
2: Only Banks 0 and Bank 1 are implemented. Selection of an unimplemented bank is not recommended.

FIGURE 7-3: TLRD INSTRUCTION OPERATION



Note 1: 8-bit value, from TABLAT (16-bit) high or low byte, loaded into register 'f'.

FIGURE 7-4: TABLRD INSTRUCTION OPERATION



Note 1: 8-bit value, from TABLAT (16-bit) high or low byte, loaded into register 'f'.
2: 16-bit value at Program Memory (TBLPTR) loaded into TABLAT register.
3: If "i" = 1, then TBLPTR = TBLPTR + 1, If "i" = 0, then TBLPTR is unchanged.

7.2 Table Writes to External Memory

Table writes to external memory are always two-cycle instructions. The second cycle writes the data to the external memory location. The sequence of events for an external memory write are the same for an internal write.

Note: If an interrupt is pending or occurs during the TABLWT, the two cycle table write completes. The RA0/INT, TMR0, or T0CKI interrupt flag is automatically cleared or the pending peripheral interrupt is acknowledged.

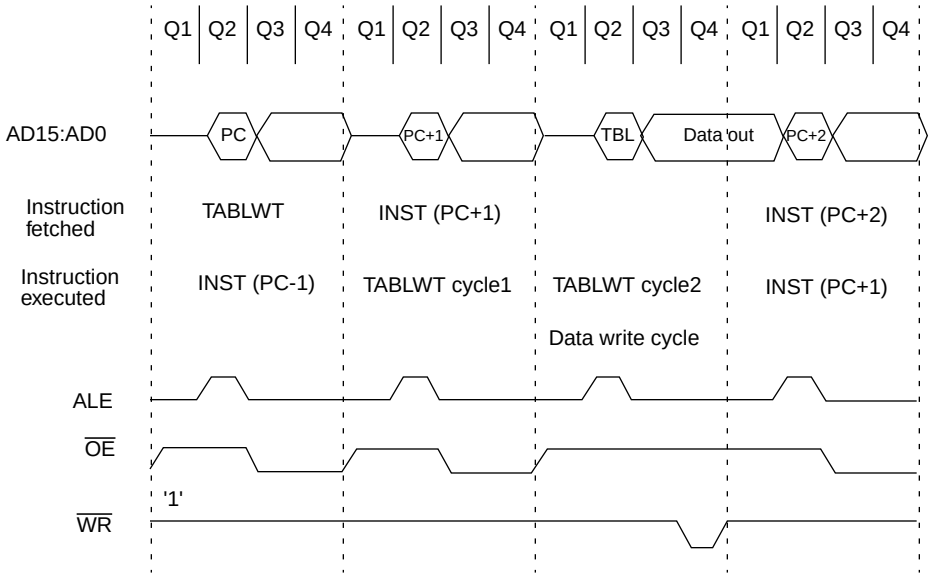
7.2.2 TABLE WRITE CODE

The "i" operand of the TABLWT instruction can specify that the value in the 16-bit TBLPTR register is automatically incremented for the next write. In Example 7-1, the TBLPTR register is not automatically incremented.

EXAMPLE 7-1: TABLE WRITE

```
CLRWDT                  ; Clear WDT
MOVLW   HIGH (TBL_ADDR) ; Load the Table
MOVWF   TBLPTRH         ;   address
MOVLW   LOW (TBL_ADDR)  ;
MOVWF   TBLPTRL         ;
MOVLW   HIGH (DATA)     ; Load HI byte
TLWT    1, WREG         ;   in TABLATCH
MOVLW   LOW (DATA)      ; Load LO byte
TABLWT  0,0,WREG        ;   in TABLATCH
                        ;   and write to
                        ;   program memory
                        ;   (Ext. SRAM)
```

FIGURE 7-5: TABLWT WRITE TIMING (EXTERNAL MEMORY)



Note: If external write GLINTD = '1', Enable bit = '1', '1' → Flag bit, Do table write. The highest pending interrupt is cleared.

NOTES:

13.1 USART Baud Rate Generator (BRG)

The BRG supports both the Asynchronous and Synchronous modes of the USART. It is a dedicated 8-bit baud rate generator. The SPBRG register controls the period of a free running 8-bit timer. Table 13-1 shows the formula for computation of the baud rate for different USART modes. These only apply when the USART is in synchronous master mode (internal clock) and asynchronous mode.

Given the desired baud rate and Fosc, the nearest integer value between 0 and 255 can be calculated using the formula below. The error in baud rate can then be determined.

TABLE 13-1: BAUD RATE FORMULA

SYNC	Mode	Baud Rate
0	Asynchronous	FOSC/(64(X+1))
1	Synchronous	FOSC/(4(X+1))

X = value in SPBRG (0 to 255)

Example 13-1 shows the calculation of the baud rate error for the following conditions:

FOSC = 16 MHz
Desired Baud Rate = 9600
SYNC = 0

EXAMPLE 13-1: CALCULATING BAUD RATE ERROR

Desired Baud rate=Fosc / (64 (X + 1))

9600 = 16000000 /(64 (X + 1))

X = 25.042 = 25

Calculated Baud Rate=16000000 / (64 (25 + 1))

= 9615

$$\text{Error} = \frac{\text{(Calculated Baud Rate - Desired Baud Rate)}}{\text{Desired Baud Rate}}$$

= (9615 - 9600) / 9600

= 0.16%

Writing a new value to the SPBRG, causes the BRG timer to be reset (or cleared), this ensures that the BRG does not wait for a timer overflow before outputting the new baud rate.

TABLE 13-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
13h, Bank 0	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00u
15h, Bank 0	TXSTA	CSRC	TX9	TXEN	SYNC	—	—	TRMT	TX9D	0000 --1x	0000 --1u
17h, Bank 0	SPBRG	Baud rate generator register								xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as a '0', shaded cells are not used by the Baud Rate Generator.
Note 1: Other (non power-up) resets include: external reset through $\overline{\text{MCLR}}$ and Watchdog Timer Reset.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

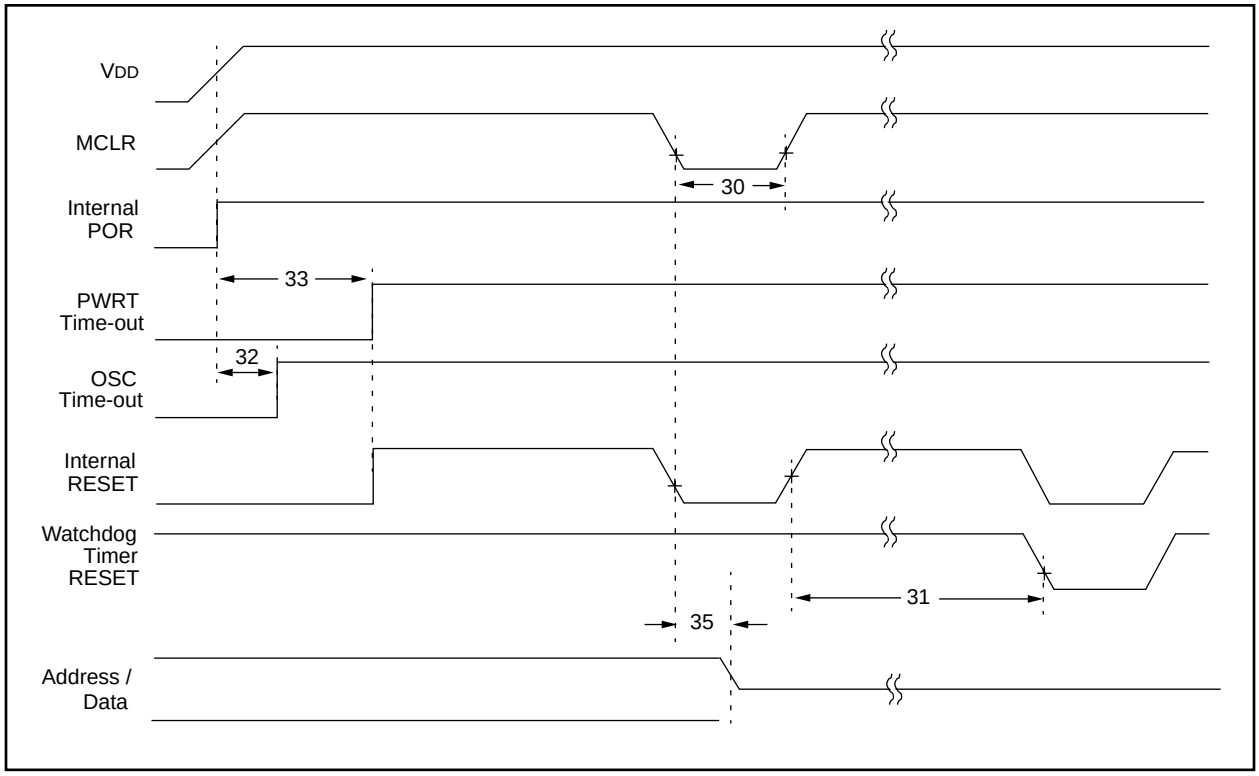


TABLE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	100 *	—	—	ns	
31	Twdt	Watchdog Timer Time-out Period (Prescale = 1)	5 *	12	25 *	ms	
32	Tost	Oscillation Start-up Timer Period		1024 TOSC §		ms	TOSC = OSC1 period
33	Tpwrt	Power-up Timer Period	40 *	96	200 *	ms	
35	TmcL2adl	$\overline{\text{MCLR}}$ to System Interface bus (AD15:AD0) invalid	—	—	100 *	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

§ This specification ensured by design.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 17-5: TIMER0 CLOCK TIMINGS

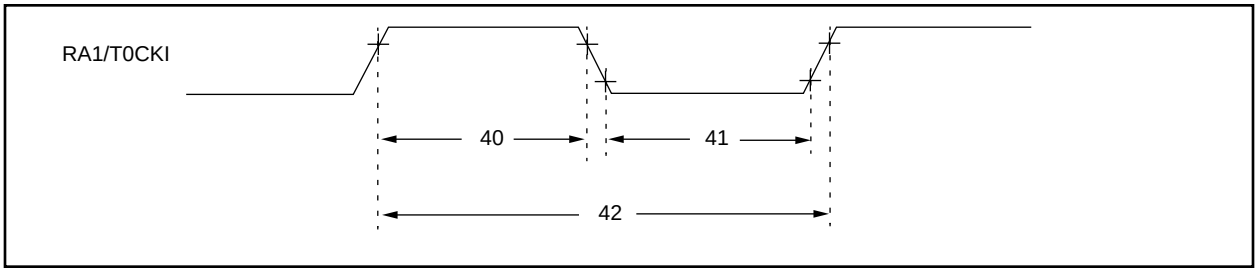


TABLE 17-5: TIMER0 CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5TCY + 20 §	—	—	ns	
			With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5TCY + 20 §	—	—	ns	
			With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period		TCY + 40 § / N	—	—	ns	N = prescale value (1, 2, 4, ..., 256)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

FIGURE 17-6: TIMER1, TIMER2, AND TIMER3 CLOCK TIMINGS

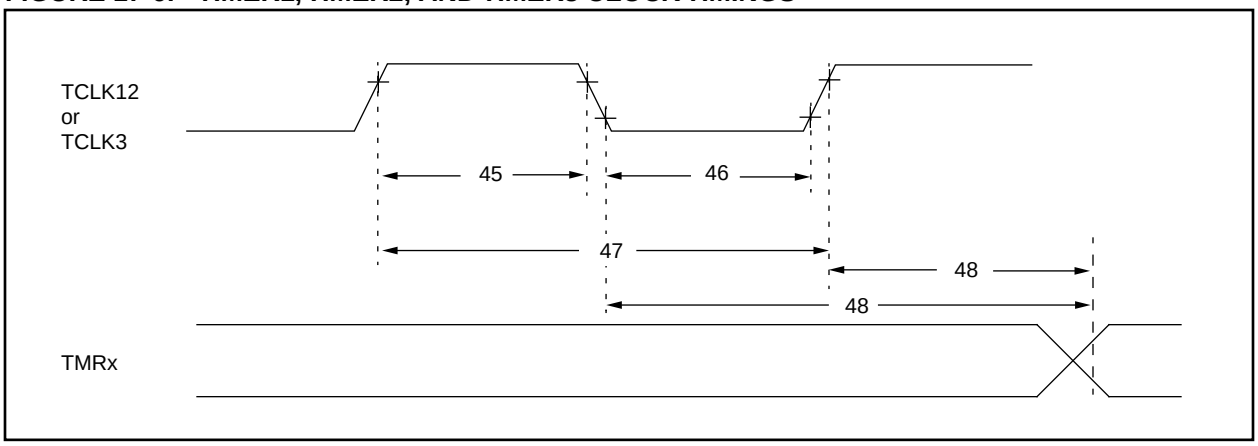


TABLE 17-6: TIMER1, TIMER2, AND TIMER3 CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ †	Max	Units	Conditions
45	Tt123H	TCLK12 and TCLK3 high time	0.5 TCY + 20 §	—	—	ns	
46	Tt123L	TCLK12 and TCLK3 low time	0.5 TCY + 20 §	—	—	ns	
47	Tt123P	TCLK12 and TCLK3 input period	TCY + 40 § / N	—	—	ns	N = prescale value (1, 2, 4, 8)
48	TckE2tmrI	Delay from selected External Clock Edge to Timer increment	2TOSC §	—	6 Tosc §	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

Applicable Devices	42	R42	42A	43	R43	44

19.1 DC CHARACTERISTICS: PIC17CR42/42A/43/R43/44-16 (Commercial, Industrial) PIC17CR42/42A/43/R43/44-25 (Commercial, Industrial) PIC17CR42/42A/43/R43/44-33 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	4.5	–	6.0	V	
D002	VDR	RAM Data Retention Voltage (Note 1)	1.5 *	–	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure internal Power-on Reset signal	–	VSS	–	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure internal Power-on Reset signal	0.060 *	–	–	mV/ms	See section on Power-on Reset for details
D010	IDD	Supply Current (Note 2)	–	3	6	mA	FOSC = 4 MHz (Note 4)
D011			–	6	12 *	mA	FOSC = 8 MHz
D012			–	11	24 *	mA	FOSC = 16 MHz
D013			–	19	38	mA	FOSC = 25 MHz
D015			–	25	50	mA	FOSC = 33 MHz
D014			–	95	150	µA	FOSC = 32 kHz, WDT enabled (EC osc configuration)
D020	IPD	Power-down Current (Note 3)	–	10	40	µA	VDD = 5.5V, WDT enabled
D021			–	< 1	5	µA	VDD = 5.5V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD or VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.
Current consumed from the oscillator and I/O's driving external capacitive or resistive loads needs to be considered.
For the RC oscillator, the current through the external pull-up resistor (R) can be estimated as: VDD / (2 • R).
For capacitive loads, the current can be estimated (for an individual I/O pin) as (CL • VDD) • f
CL = Total capacitive load on the I/O pin; f = average frequency the I/O pin switches.
The capacitive currents are most significant when the device is configured for external execution (includes extended microcontroller mode).

3: The power down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula IR = VDD/2Rext (mA) with Rext in kOhm.

Applicable Devices	42	R42	42A	43	R43	44

19.3 DC CHARACTERISTICS: PIC17CR42/42A/43/R43/44-16 (Commercial, Industrial) PIC17CR42/42A/43/R43/44-25 (Commercial, Industrial) PIC17CR42/42A/43/R43/44-33 (Commercial, Industrial) PIC17LCR42/42A/43/R43/44-08 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in Section 19.1				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
		Input Low Voltage					
	VIL	I/O ports					
D030		with TTL buffer	VSS	–	0.8	V	4.5V ≤ VDD ≤ 5.5V
			VSS	–	0.2VDD	V	2.5V ≤ VDD ≤ 4.5V
D031		with Schmitt Trigger buffer	VSS	–	0.2VDD	V	
D032		$\overline{MCLR}$, OSC1 (in EC and RC mode)	Vss	–	0.2VDD	V	Note1
D033		OSC1 (in XT, and LF mode)	–	0.5VDD	–	V	
		Input High Voltage					
	VIH	I/O ports					
D040		with TTL buffer	2.0	–	VDD	V	4.5V ≤ VDD ≤ 5.5V
			1 + 0.2VDD	–	VDD	V	2.5V ≤ VDD ≤ 4.5V
D041		with Schmitt Trigger buffer	0.8VDD	–	VDD	V	
D042		$\overline{MCLR}$	0.8VDD	–	VDD	V	Note1
D043		OSC1 (XT, and LF mode)	–	0.5VDD	–	V	
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15VDD *	–	–	V	
		Input Leakage Current (Notes 2, 3)					
D060	IIL	I/O ports (except RA2, RA3)	–	–	±1	µA	Vss ≤ VPIN ≤ VDD, I/O Pin at hi-impedance PORTB weak pull-ups disabled
D061		$\overline{MCLR}$	–	–	±2	µA	VPIN = Vss or VPIN = VDD
D062		RA2, RA3			±2	µA	Vss ≤ VRA2, VRA3 ≤ 12V
D063		OSC1, TEST (EC, RC modes)	–	–	±1	µA	Vss ≤ VPIN ≤ VDD
D063B		OSC1, TEST (XT, LF modes)	–	–	VPIN	µA	RF ≥ 1 MΩ, see Figure 14.2
D064		$\overline{MCLR}$	–	–	10	µA	VMCLR = VPP = 12V (when not programming)
D070	IPURB	PORTB weak pull-up current	60	200	400	µA	VPIN = VSS, $\overline{RBPU}$ = 0 4.5V ≤ VDD ≤ 6.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC17CXX devices be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: These specifications are for the programming of the on-chip program memory EPROM through the use of the table write instructions. The complete programming specifications can be found in: PIC17CXX Programming Specifications (Literature number DS30139).

5: The $\overline{MCLR}$/VPP pin may be kept in this range at times other than programming, but is not recommended.

6: For TTL buffers, the better of the two specifications may be used.

Applicable Devices	42	R42	42A	43	R43	44

19.5 Timing Diagrams and Specifications

FIGURE 19-2: EXTERNAL CLOCK TIMING

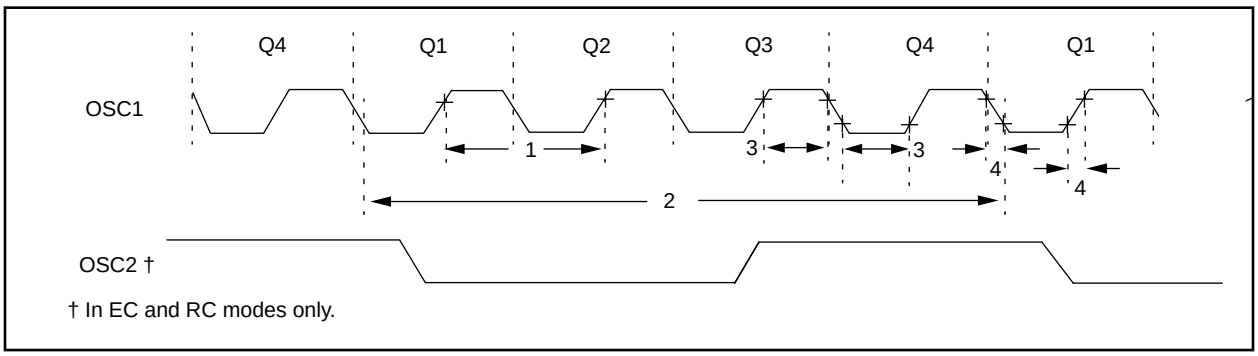


TABLE 19-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	**External CLKIN Frequency (Note 1)**	DC	—	8	MHz	EC osc mode - 08 devices (8 MHz devices)
			DC	—	16	MHz	- 16 devices (16 MHz devices)
			DC	—	25	MHz	- 25 devices (25 MHz devices)
			DC	—	33	MHz	- 33 devices (33 MHz devices)
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			1	—	8	MHz	XT osc mode - 08 devices (8 MHz devices)
			1	—	16	MHz	- 16 devices (16 MHz devices)
			1	—	25	MHz	- 25 devices (25 MHz devices)
			1	—	33	MHz	- 33 devices (33 MHz devices)
			DC	—	2	MHz	LF osc mode
1	Tosc	**External CLKIN Period (Note 1)**	125	—	—	ns	EC osc mode - 08 devices (8 MHz devices)
			62.5	—	—	ns	- 16 devices (16 MHz devices)
			40	—	—	ns	- 25 devices (25 MHz devices)
			30.3	—	—	ns	- 33 devices (33 MHz devices)
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			125	—	1,000	ns	XT osc mode - 08 devices (8 MHz devices)
			62.5	—	1,000	ns	- 16 devices (16 MHz devices)
			40	—	1,000	ns	- 25 devices (25 MHz devices)
			30.3	—	1,000	ns	- 33 devices (33 MHz devices)
			500	—	—	ns	LF osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	121.2	4/Fosc	DC	ns	
3	TosL, TosH	**Clock in (OSC1) high or low time**	10 ‡	—	—	ns	EC oscillator
4	TosR, TosF	**Clock in (OSC1) rise or fall time**	—	—	5 ‡	ns	EC oscillator

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "max." cycle time limit is "DC" (no clock) for all devices.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-5: TRANSCONDUCTANCE (gm) OF LF OSCILLATOR vs. VDD

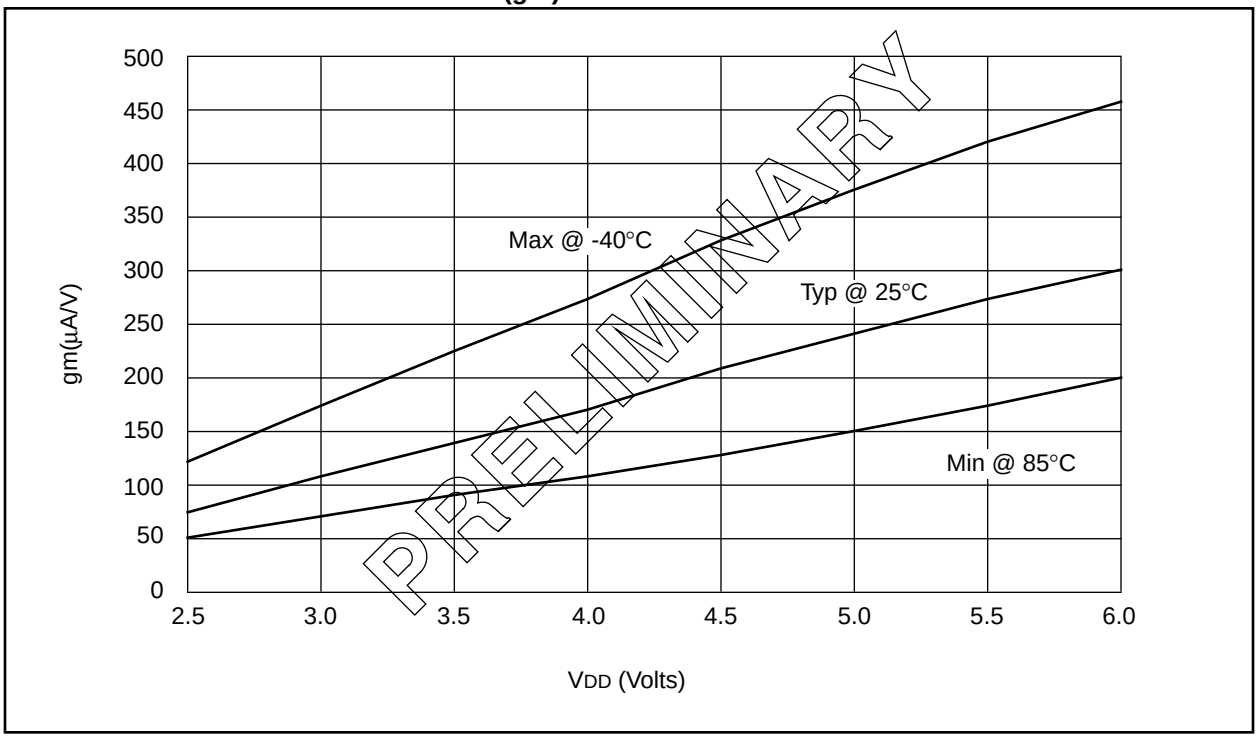
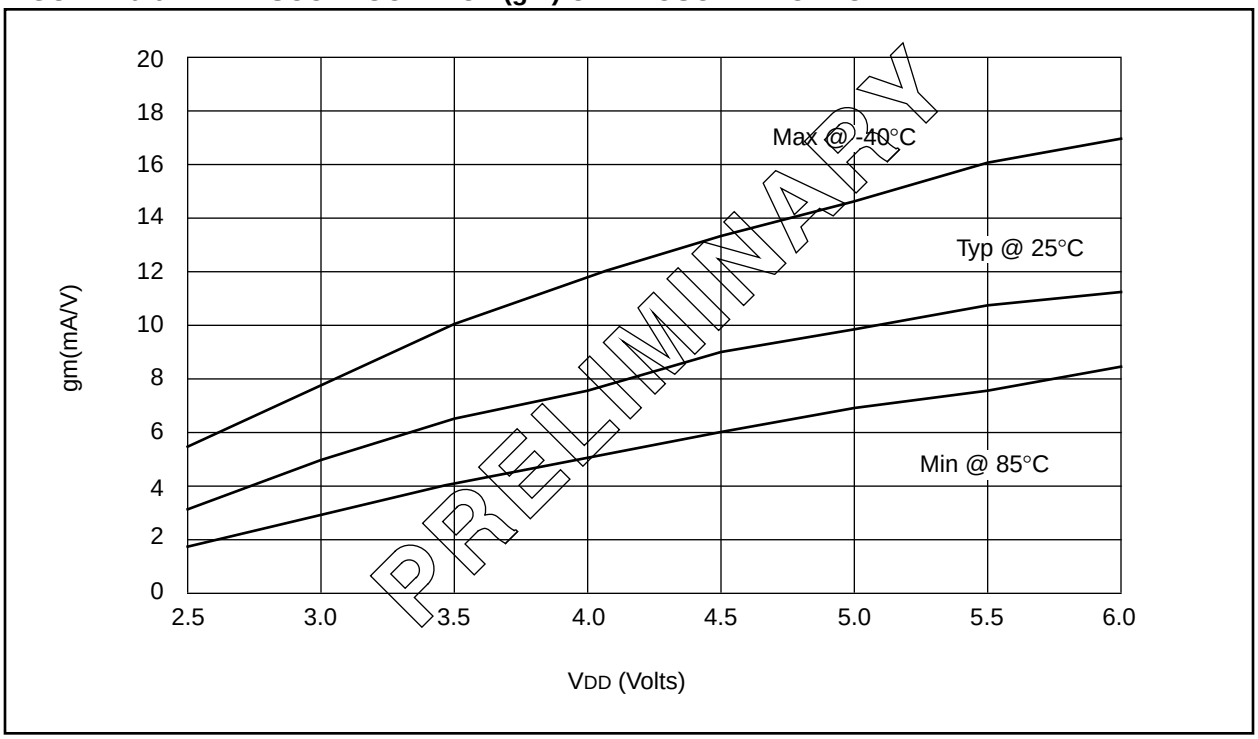


FIGURE 20-6: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD



Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-7: TYPICAL IDD vs. FREQUENCY (EXTERNAL CLOCK 25°C)

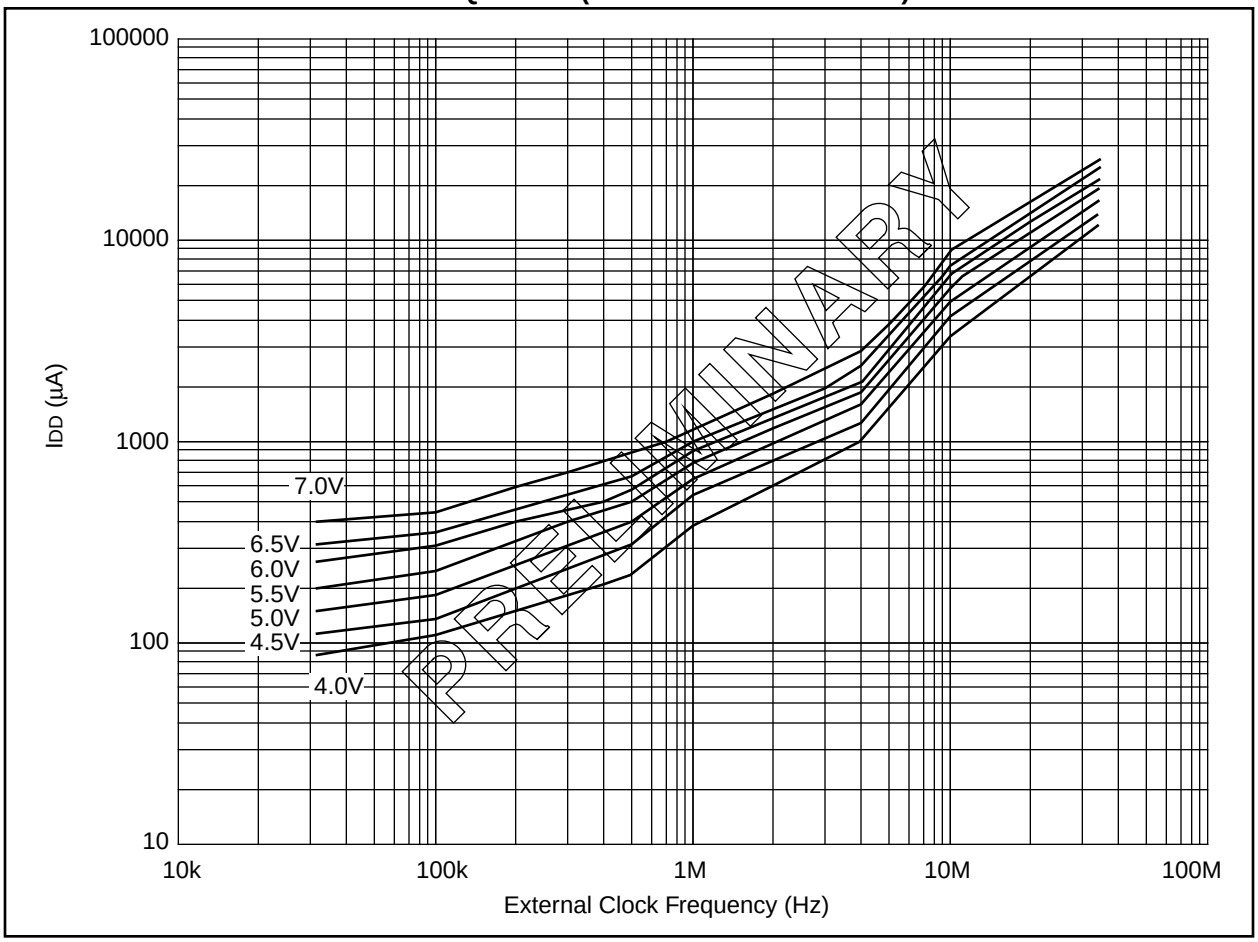
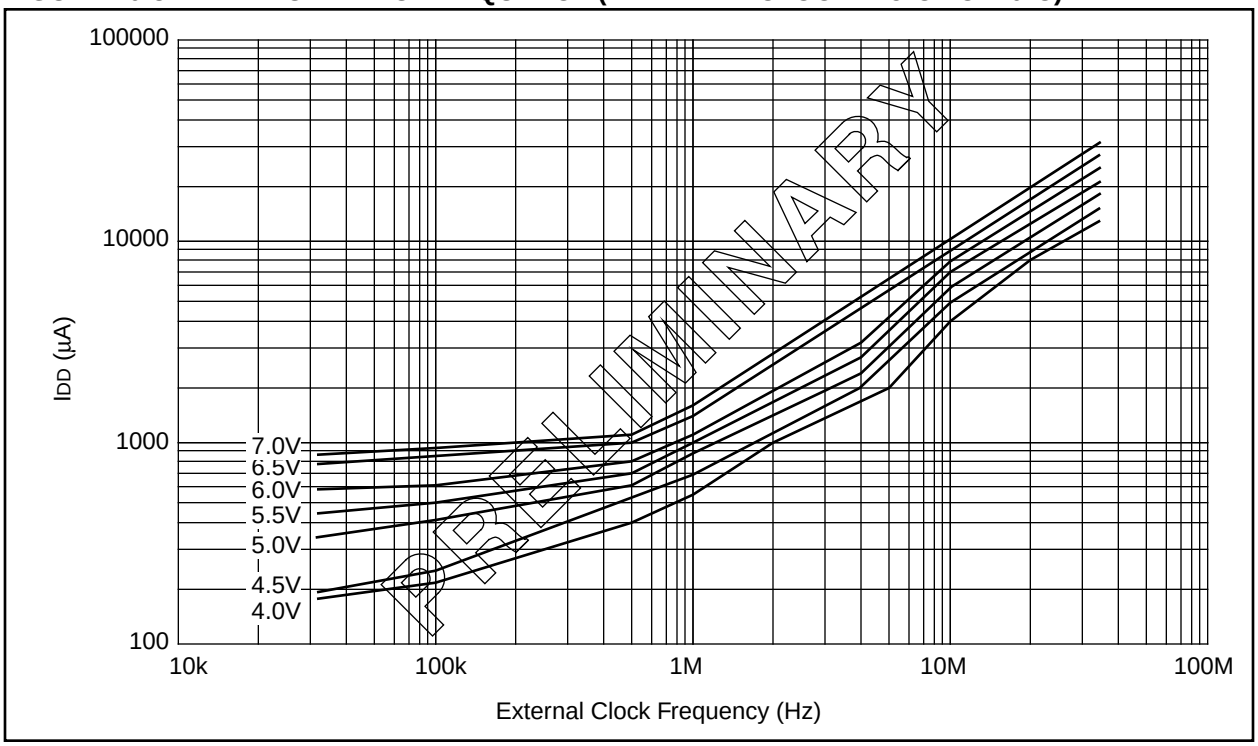


FIGURE 20-8: MAXIMUM IDD vs. FREQUENCY (EXTERNAL CLOCK 125°C TO -40°C)



Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-9: TYPICAL IPD vs. VDD WATCHDOG DISABLED 25°C

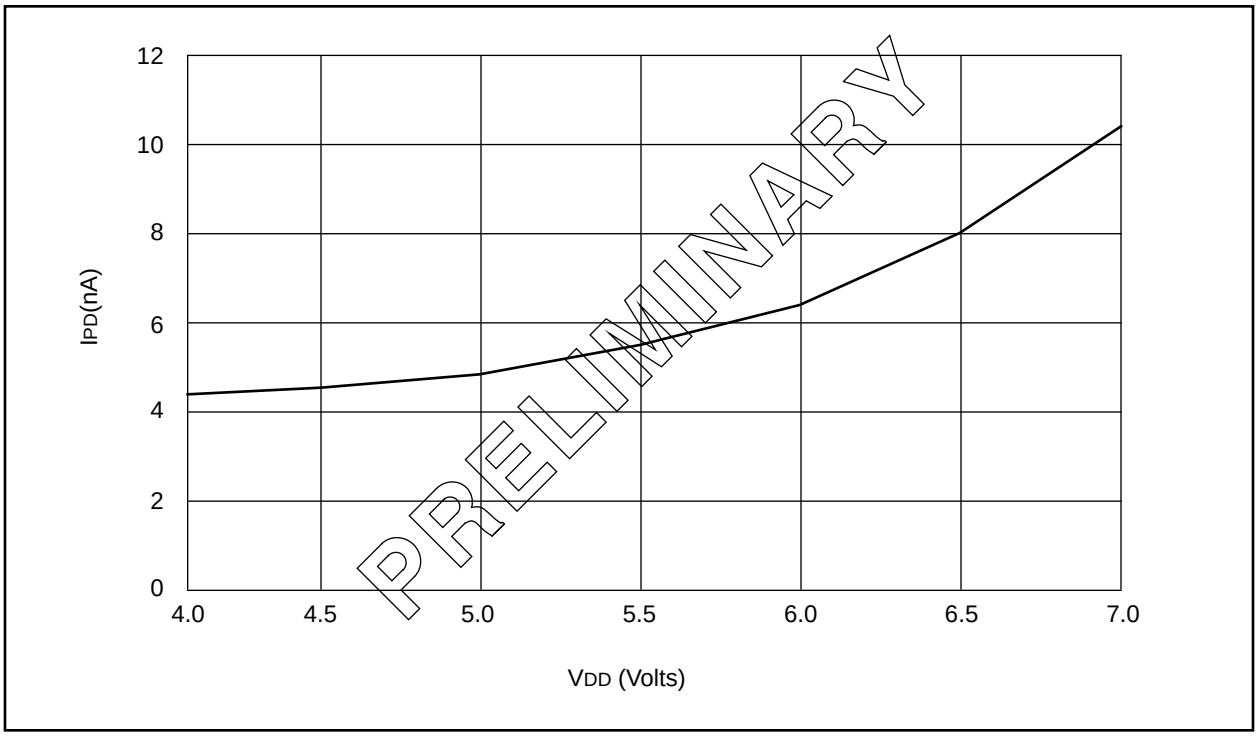
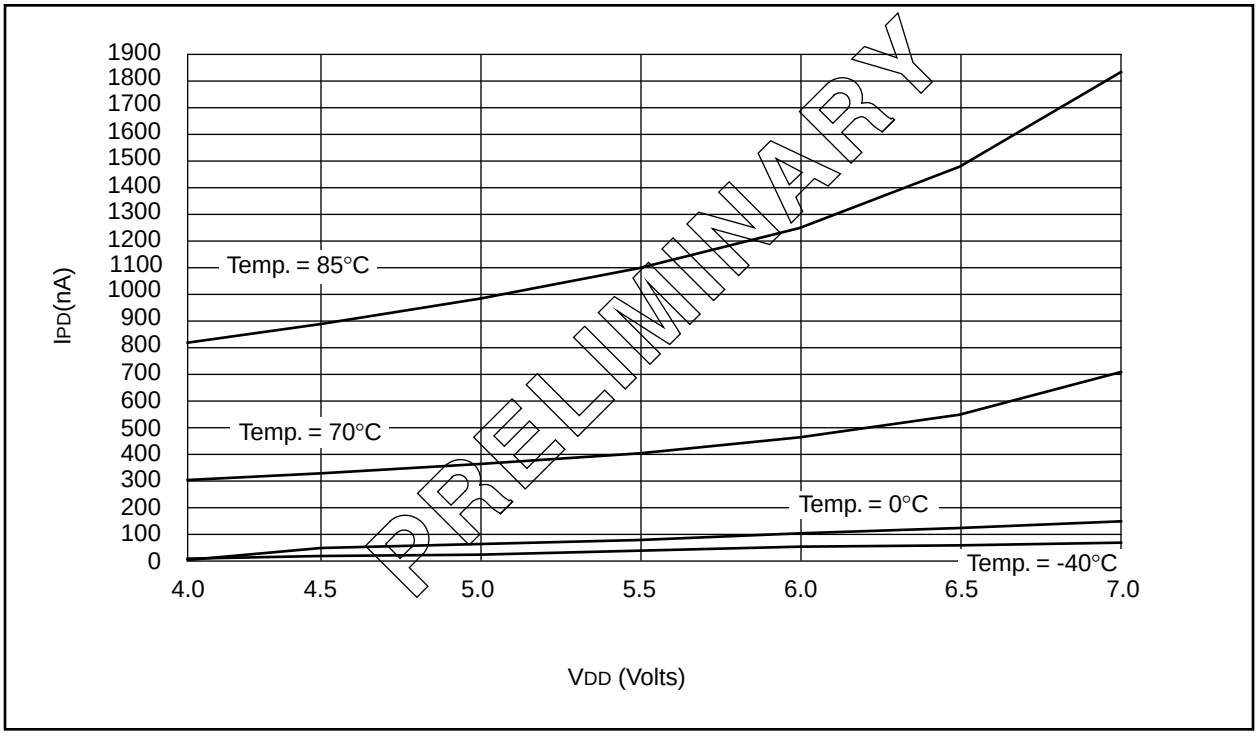


FIGURE 20-10: MAXIMUM IPD vs. VDD WATCHDOG DISABLED



Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-15: IOH vs. VOH, VDD = 5V

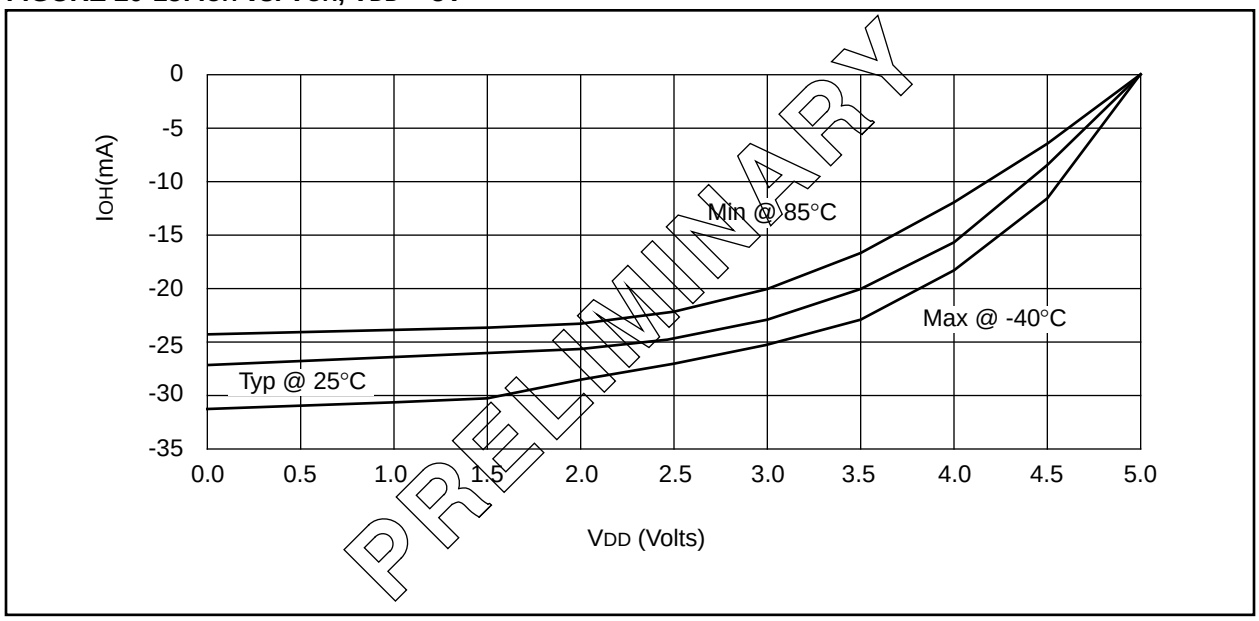
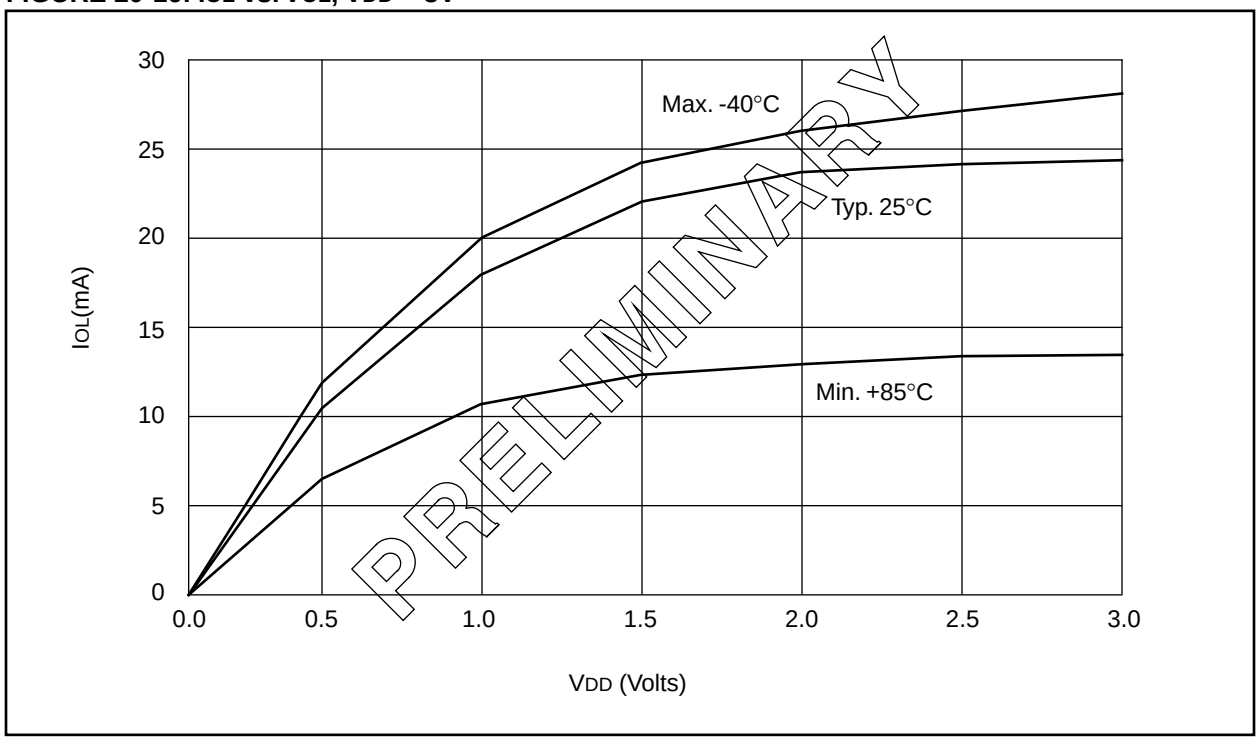


FIGURE 20-16: IOL vs. VOL, VDD = 3V



E.6 PIC16C8X Family of Devices

	Clock	Memory				Peripherals		Features		
	Maximum Frequency of Operation (MHz)	Program Memory	Flash	EEPROM	ROM	Data Memory (bytes)	Data EEPROM (bytes)	Timer Module(s)	Interrupt Sources	I/O Pins	Voltage Range (Volts)	Packages
PIC16C84	10	—	1K	—	36	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC
PIC16F84(1)	10	1K	—	—	68	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC
PIC16CR84(1)	10	—	—	1K	68	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC
PIC16F83(1)	10	512	—	—	36	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC
PIC16CR83(1)	10	—	—	512	36	64		TMR0	4	13	2.0-6.0	18-pin DIP, SOIC

All PIC16/17 family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect, and high I/O current capability.

All PIC16C8X family devices use serial programming with clock pin RB6 and data pin RB7.

Note 1: Please contact your local sales office for availability of these devices.

X

Z

LIST OF EXAMPLES

LIST OF FIGURES

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